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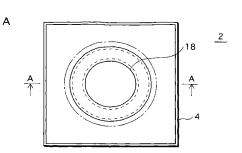
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- (71) Applicant (for all designated States except US): MAT-SUSHITA ELECTRIC INDUSTRIAL CO., LTD. [JP/JP]; 1006, Oaza Kadoma, Kadoma-shi, Osaka, 5718501 (JP).
- (72) Inventor; and
- (75) Inventor/Applicant (for US only): NAGAI, Hideo.

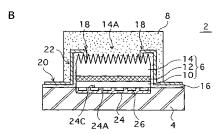
- (74) Agents: NAKAJIMA, Shiro et al.; 6F, Yodogawa 5-Bankan, 2-1, Toyosaki 3-chome, Kita-ku Osaka-shi, Osaka, 5310072 (JP).
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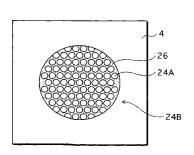
(54) Title: NITRIDE BASED LED WITH A P-TYPE INJECTION REGION



(57) Abstract: An LED chip (2) is composed of a p-GaN layer (10), an n-GaN layer (14), and an MQW emission layer (12) that is sandwiched between the GaN layers (10 and 14). Each layer is made of a GaN semiconductor. Light exits the LED chip (2) through the n-GaN layer (14). A p-electrode (16) of the LED chip (2) has a surface profile (24B) defined by a plurality of columnar projections (24A) formed in a uniformly distributed relation on the surface facing toward the p-GaN layer (10). The p-electrode (16) is in contact with the p-GaN layer (10) at the top surface of each projection (24A).



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